

Technical documentation



Support & training



SBOSAB2A - FEBRUARY 2023 - REVISED JULY 2023

OPA2863-Q1 Automotive, Low-Power, 110-MHz, Rail-to-Rail Input/Output Amplifier

1 Features

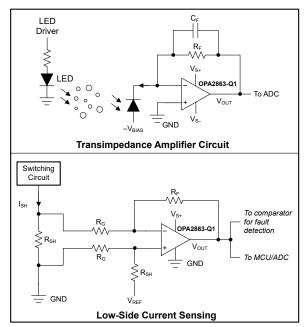
TEXAS

INSTRUMENTS

- AEC-Q100 qualified for automotive applications:
 Temperature grade 1: -40°C to +125°C, T_A
- Wide-bandwidth
 - Unity-gain bandwidth: 110 MHz
 - Gain-bandwidth product: 50 MHz
- Low power
 - Quiescent current: 700 µA/ch (typical)
 - Supply voltage: 2.7 V to 12.6 V
- Input voltage noise: 5.9 nV/√Hz
- Slew rate: 105 V/µs
- Rail-to-rail input and output
- HD₂/HD₃: –129 dBc/–138 dBc at 20 kHz (2 V_{PP})
- Additional features:
 - Overload power limit
 - Output short-circuit protection

2 Applications

- Low-side current sensing
- DC/DC converters
- Inverter and motor control
- Onboard and wireless chargers
- HVAC compressors
- Photodiode TIA interface
- Head-up display (HUD)



Application Circuits Using the OPA2863-Q1

3 Description

The OPA2863-Q1 is a low-power, unity-gain stable, rail-to-rail input and output, voltage-feedback operational amplifier designed to operate over a power-supply range of 2.7 V to 12.6 V. Consuming only 700 μ A per channel, the OPA2863-Q1 offers a gain-bandwidth product of 50 MHz, slew rate of 105 V/ μ s with a voltage noise density of 5.9 nV/ \sqrt{Hz} .

The rail-to-rail input stage makes OPA2863-Q1 an excellent choice for general-purpose applications like current sensing and photodiode interface. The rail-to-rail input stage is well-matched for gain-bandwidth product and noise across the full input common-mode voltage range, enabling excellent performance with wide-input dynamic range.

The OPA2863-Q1 includes overload power limiting to limit the increase in I_Q with saturated outputs, thereby preventing excessive power dissipation in power-conscious, battery-operated systems. The output stage is short-circuit protected, making these devices conducive to ruggedized environments.

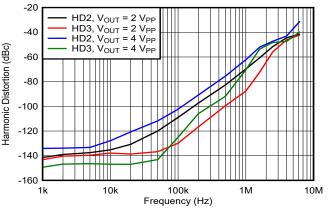
Package Information

PART NUMBER ⁽¹⁾	PACKAGE ⁽²⁾	PACKAGE SIZE ⁽³⁾		
OPA2863-Q1	D (SOIC, 8)	4.9 mm × 6 mm		

(1) For related products, see the *Device Comparison Table*.

(2) For all available packages, see the orderable addendum at the end of the data sheet.

(3) The package size (length × width) is a nominal value and includes pins, where applicable.



Distortion Performance at G = 1 V/V

An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Cł	nanges from Revision * (February 2023) to Revision A (July 2023)	Page
•	Changed data sheet status from advanced information (preview) to production data (active)	1



5 Device Comparison Table

DEVICE	±V _S (V)	l _Q /CHANNEL (mA)	GBWP (MHz)	SLEW RATE (V/µs)	VOLTAGE NOISE (nV/√ Hz)	AMPLIFIER DESCRIPTION	
OPA2863-Q1	±6.3	0.70	50	105	5.9	Unity-gain-stable. RRIO bipolar amplifier	
OPA2365-Q1	±2.75	4.6	50	25	4.5	Unity-gain-stable, zero-crossover, RRIO CMOS amplifier	
OPA2607-Q1	±2.75	0.9	50	24	3.8	Gain of 6 V/V stable, NRI/RRO CMOS amplifier	
OPA2836-Q1	±2.75	1	110	560	4.6	Unity-gain stable, low-power, NRI/RRO bipolar amplifier	

6 Pin Configuration and Functions

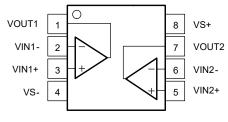


Figure 6-1. D Package, 8-Pin SOIC (Top View)

Table 6-1. Pin Functions

	PIN		DESCRIPTION		
NAME NO.		TYPE ⁽¹⁾	DESCRIPTION		
VIN1-	2	I	Amplifier 1 inverting input pin		
VIN1+	3	I	Amplifier 1 noninverting input pin		
VIN2–	6	I	mplifier 2 inverting input pin		
VIN2+	5	I	mplifier 2 noninverting input pin		
VOUT1	1	0	nplifier 1 output pin		
VOUT2	7	0	Amplifier 2 output pin		
VS-	4	Р	Negative power-supply pin		
VS+	8	Р	Positive power-supply pin		

(1) I = input, O = output, and P = power.



7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V_{S-} to V_{S+}	Supply voltage		13	V
	Supply turn-on/off maximum dV/dt		1	V/µs
VI	Input voltage	V _{S-} -0.5	V _{S+} + 0.5	V
V _{ID}	Differential input voltage		±1	V
l _l	Continuous input current ⁽²⁾		±10	mA
I _O	Continuous output current ⁽³⁾		±30	mA
	Continuous power dissipation	See Thermal I	nformation	
TJ	Junction temperature		150	°C
T _A	Operating ambient temperature	-40	125	°C
T _{stg}	Storage temperature	-65	150	°C

(1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.

(2) Continuous input current limit for both the ESD diodes to the supply pins and amplifier differential input clamp diode. The differential input clamp diodes limit the voltage between the two inputs to 1 V with this continuous input current flowing through these diodes.

(3) Long-term continuous current for electromigration limits.

7.2 ESD Ratings

			VALUE	UNIT
Electrostatic	Human body model (HBM), per AEC Q100-002 ⁽¹⁾ HBM ESD classification level 2	±2000	M	
V _(ESD)	discharge	Charged device model (CDM), per AEC Q100-011 CDM ESD classification level C6	±1000	v

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with ANSI/ESDA/JEDEC JS-001 specification.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
$V_{S+} - V_{S-}$	Total supply voltage	2.7	10	12.6	V
T _A	Ambient temperature	-40	25	125	°C

7.4 Thermal Information

		OPA2863-Q1	
	THERMAL METRIC ⁽¹⁾	D (SOIC)	UNIT
		8 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	120.0	°C/W
R _{0JC(top)}	Junction-to-case (top) thermal resistance	63.3	°C/W
R _{θJB}	Junction-to-board thermal resistance	63.2	°C/W
Ψ _{JT}	Junction-to-top characterization parameter	17.2	°C/W
Y _{JB}	Junction-to-board characterization parameter	62.5	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.



7.5 Electrical Characteristics: $V_S = \pm 5 V$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
AC PER	FORMANCE						
SSBW	Small-signal bandwidth	V _{OUT} = 20 mV _{PP} , G = 1		110		MHz	
GBWP	Gain-bandwidth product			50		MHz	
LSBW	Large-signal bandwidth	V _{OUT} = 2 V _{PP}		17		MHz	
	Bandwidth for 0.1-dB flatness	V _{OUT} = 20 mV _{PP}		15		MHz	
SR	Slew rate	V _{OUT} = 2-V step, G = -1		105		V/µs	
	Rise, fall time	V _{OUT} = 200-mV step		9		ns	
		To 0.1%, V _{OUT} = 2-V step		57		-	
	Settling time	To 0.01%, V _{OUT} = 2-V step		70		ns	
	Overshoot/undershoot	V _{OUT} = 2-V step		1		%	
		G = -1, 0.5-V overdrive beyond supplies		70			
	Overdrive recovery time	G = 1, 0.5-V overdrive beyond supplies		100		ns	
HD2	Second-order harmonic distortion	f = 20 kHz, V _{OUT} = 2 V _{PP}		-129		dBc	
HD3	Third-order harmonic distortion	f = 20 kHz, V _{OUT} = 2 V _{PP}		-138		dBc	
HD2	Second-order harmonic distortion	f = 100 kHz, V _{OUT} = 2 V _{PP}		-107		dBc	
HD3	Third-order harmonic distortion	f = 100 kHz, V _{OUT} = 2 V _{PP}		-125		dBc	
e _N	Input voltage noise	1/f corner at 25 Hz		5.9		nV/√Hz	
i _N	Input current noise	1/f corner at 2 kHz		0.4		pA/√Hz	
	Closed-loop output impedance	f = 1 MHz		0.2		Ω	
	Channel-to-channel crosstalk	f = 1 MHz, V _{OUT} = 2 V _{PP}		-124		dBc	
DC PER	FORMANCE	· · · ·					
A _{OL}	Open-loop voltage gain	V _{OUT} = ±2.5 V	110	128		dB	
V _{OS}	Input-referred offset voltage		-1.5	±0.4	1.5	mV	
	Input offset voltage drift	$T_A = -40^{\circ}C$ to $+125^{\circ}C$	-4	±1	4	µV/°C	
		T _A ≅25°C		0.3	0.73		
	Input bias current	$T_A = -40^{\circ}C$ to $+85^{\circ}C$			1.2	μA	
		$T_A = -40^{\circ}C$ to $+125^{\circ}C$			1.6		
	Input bias current drift	$T_A = -40^{\circ}C$ to $+125^{\circ}C$		±3	7.6	nA/°C	
	Input offset current		-30	±10	30	nA	
INPUT	-	· · · ·					
	Input common-mode voltage		V _{S-} -0.2		V _{S+} +0.2	V	
CMRR	Common-mode rejection ratio	$V_{CM} = V_{S-} - 0.2 \text{ V to } V_{S+} - 1.6 \text{ V}$	100	120		dB	
	Input impedance common-mode			650 0.8		MΩ pF	
	Input impedance differential mode			200 0.5		kΩ pF	
Ουτρυτ	r i	· · · · · ·					
		T _A ≅ 25°C		V _{S-} +0.14	V _{S-} +0.2		
V _{OL}	Output voltage, low	$T_A = -40^{\circ}C$ to $+125^{\circ}C$		V _{S-} +0.15	V _{S-} +0.22	V	
	Quality of the new latest	T _A ≅ 25°C	V _{S+} -0.2	V _{S+} -0.14			
V _{OH}	Output voltage, high	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$	V _{S+} -0.2	V _{S+} -0.15		V	
	Linear output drive (sourcing and sinking)	V_{OUT} = ±2.5 V, ΔV_{OS} < 1 mV ⁽¹⁾	25	30		mA	
	Short-circuit current			45		mA	

7.5 Electrical Characteristics: V_S = ±5 V (continued)

at G = 1 V/V, $R_F = 0 \Omega$ for G = 1 V/V, otherwise $R_F = 1 k\Omega$ for other gains, $C_L = 1 pF$, $R_L = 2 k\Omega$ referenced to mid-supply, input and output common-mode is at mid-supply, and $T_A \cong 25^{\circ}C$ (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT		
POWER SUPPLY								
		T _A ≅ 25°C		700	970			
l _Q	Quiescent current per amplifier	$T_A = -40^{\circ}C$ to +125°C			1280	μA		
PSRR	Power-supply rejection ratio	$\Delta V_{\rm S} = \pm 2 \ V^{(2)}$	100	120		dB		
AUXILIA	ARY INPUT STAGE							
	Gain-bandwidth product			50		MHz		
	Input voltage noise	1/f corner at 25 Hz		6		nV/√Hz		
	Input current noise	1/f corner at 100 Hz		0.4		pA/√Hz		
	Input-referred offset voltage		-1.5	±0.15	1.5	mV		
		T _A ≅ 25°C		0.2	0.6			
	Input bias current	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$			1.3	μA		
	Common-mode rejection ratio	V _{CM} = 4.1 V to 5.2 V	100	120		dB		
	Power supply rejection ratio	$\Delta V_{\rm S} = \pm 0.6 \text{ V}$	100	120		dB		
		1						

(1) Change in input offset voltage from no-load condition.

(2) Change in supply voltage from the default test condition with only one of the positive or negative supplies changing corresponding to +PSRR and -PSRR.

7.6 Electrical Characteristics: V_S = 3 V

at G = 1 V/V, $R_F = 0 \Omega$ for G =1 V/V, otherwise $R_F = 1 k\Omega$ for other gains, $C_L = 1 pF$, $R_L = 2 k\Omega$ connected to 1 V, input and output $V_{CM} = 1 V$, and $T_A \cong 25^{\circ}C$ (unless otherwise noted)

PARAMETER		PARAMETER TEST CONDITIONS			
AC PER	FORMANCE	· · ·			
SSBW	Small-signal bandwidth	V _{OUT} = 20 mV _{PP} , G = 1	97		MHz
GBWP	Gain-bandwidth product		50		MHz
LSBW	Large-signal bandwidth	V _{OUT} = 1 V _{PP}	26		MHz
	Bandwidth for 0.1-dB flatness	V _{OUT} = 20 mV _{PP}	10		MHz
SR	Slew rate	V _{OUT} = 1-V step, G = -1	105		V/µs
Rise, fall time	V _{OUT} = 200-mV step	10		ns	
	Cattling time	To 0.1%, V _{OUT} = 1-V step	58		
	Settling time	To 0.01%, V _{OUT} = 1-V step			ns
	Overshoot	V _{OUT} = 1-V step	2		%
	Undershoot	V _{OUT} = 1-V step	16		%
		G = -1, 0.5-V overdrive beyond supplies			
	Overdrive recovery time	G = 1, 0.5-V overdrive beyond supplies	100		ns
HD2	Second-order harmonic distortion	f = 20 kHz, V _{OUT} = 1 V _{PP}	-123		dBc
HD3	Third-order harmonic distortion	f = 20 kHz, V _{OUT} = 1 V _{PP}	-132		dBc
HD2	Second-order harmonic distortion	f = 100 kHz, V _{OUT} = 1 V _{PP}	-109		dBc
HD3	Third-order harmonic distortion	f = 100 kHz, V _{OUT} = 1 V _{PP}	-129		dBc
e _N	Input voltage noise	1/f corner at 25 Hz	6		nV/√Hz
i _N	Input current noise	1/f corner at 2 kHz	0.4		pA/√Hz
	Closed-loop output impedance	f = 1 MHz	0.2		Ω
	Channel-to-channel crosstalk	f = 1 MHz, V _{OUT} = 1 V _{PP}	-127		dBc

7.6 Electrical Characteristics: V_S = 3 V (continued)

at G = 1 V/V, $R_F = 0 \Omega$ for G =1 V/V, otherwise $R_F = 1 k\Omega$ for other gains, $C_L = 1 pF$, $R_L = 2 k\Omega$ connected to 1 V, input and output $V_{CM} = 1 V$, and $T_A \cong 25^{\circ}C$ (unless otherwise noted)

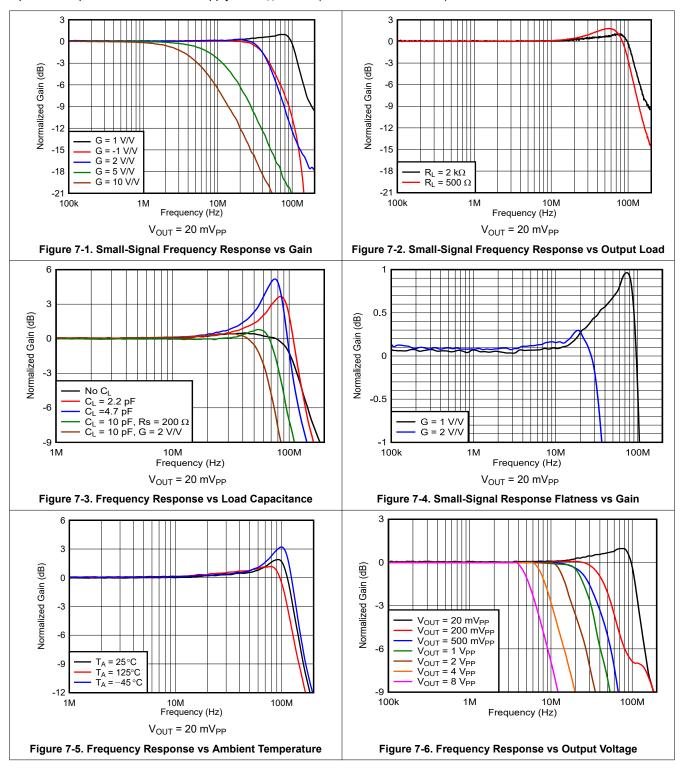
	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
DC PER	FORMANCE		·				
A _{OL}	Open-loop voltage gain	V _{OUT} = 1 V to 2 V	104	123		dB	
V _{OS}	Input-referred offset voltage		-1.5	±0.4	1.5	mV	
	Input offset voltage drift	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$	-4	±1	4	µV/°C	
		T _A ≅ 25°C		0.3	0.73		
	Input bias current	$T_A = -40^{\circ}C$ to $+85^{\circ}C$			1.2	μA	
		$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$			1.6		
	Input bias current drift	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$		±3	7.4	nA/°C	
	Input offset current		-30	±10	30	nA	
INPUT		,	i				
	Input common-mode voltage		V _{S-} -0.2		V _{S+} +0.2	V	
CMRR	Common-mode rejection ratio	$V_{CM} = V_{S-} - 0.2 \text{ V to } V_{S+} - 1.6 \text{ V}$	94	115		dB	
	Input impedance common-mode			360 0.9		MΩ pF	
	Input impedance differential mode			200 0.5		kΩ pF	
OUTPU	r					1	
		T _A ≅ 25°C		V _{S-} + 0.13	V _S _+ 0.15	V	
V _{OL} Output voltage, low	Output voltage, low	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$		V _{S-} + 0.13	V _{S-} + 0.16	v	
	Output voltage, high	T _A ≅25°C	V _{S+} -0.15	V _{S+} 0.13		V	
V _{OH}		$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$	V _{S+} -0.15	V _{S+} -0.13		V	
	Linear output drive (sourcing and sinking)	$V_{OUT} = \pm 0.7 \text{ V}, \Delta V_{OS} < 1 \text{ mV}^{(1)}$	23	33		mA	
	Short-circuit current			45		mA	
POWER	SUPPLY	,					
		T _A ≅ 25°C		690	910		
l _Q	Quiescent current per amplifier	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$			1180	μA	
PSRR	Power-supply rejection ratio	$\Delta V_{\rm S} = \pm 1 \ V^{(2)}$	100	120		dB	
AUXILIA	ARY INPUT STAGE						
	Gain-bandwidth product			50		MHz	
	Input voltage noise	1/f corner at 25 Hz		6		nV/√Hz	
	Input current noise	1/f corner at 100 Hz		0.4		pA/√Hz	
	Input-referred offset voltage		-1.5	±0.15	1.5	mV	
	land block and the	T _A ≅ 25°C		0.2	0.6		
	Input bias current	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$			1.2	μA	
	Common-mode rejection ratio	V _{CM} = 2.1 V to 3.2 V	100	120		dB	
	Power supply rejection ratio	$\Delta V_{\rm S} = \pm 0.6 \text{ V}$	100	115		dB	

(1) Change in input offset voltage from no-load condition.

(2) Change in supply voltage from the default test condition with only one of the positive or negative supplies changing corresponding to +PSRR and -PSRR.

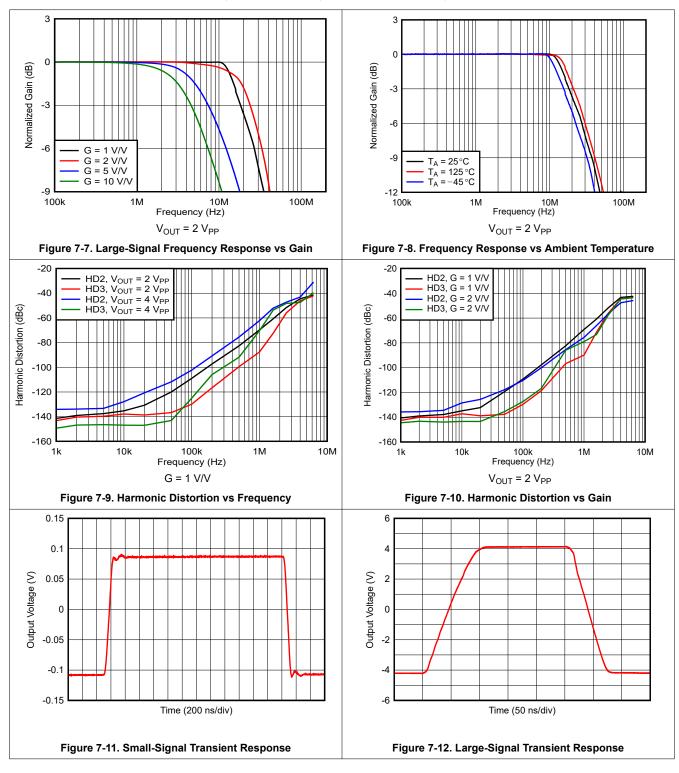


7.7 Typical Characteristics: V_S = ±5 V



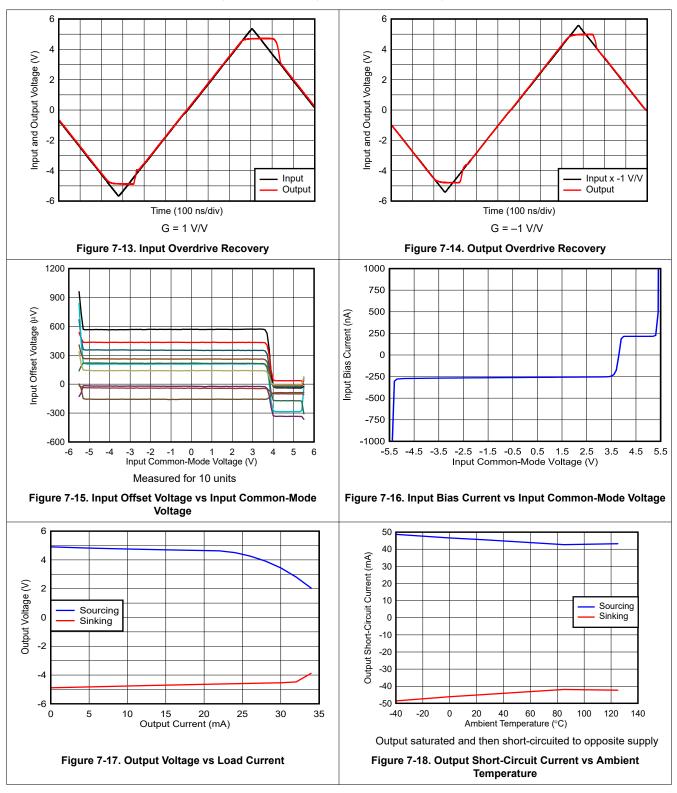


7.7 Typical Characteristics: V_S = ±5 V (continued)



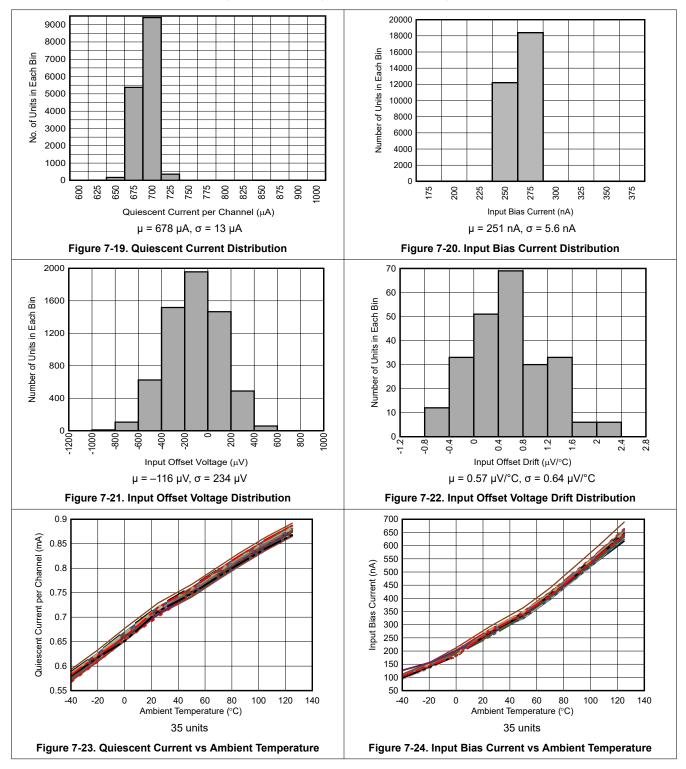


7.7 Typical Characteristics: $V_S = \pm 5 V$ (continued)



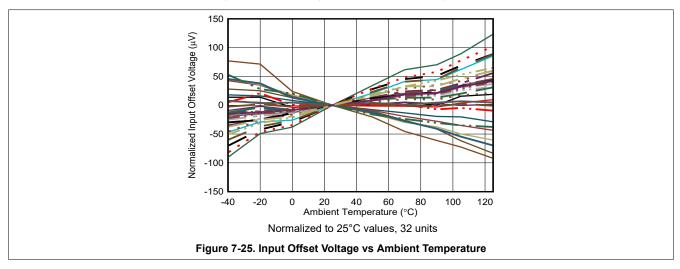


7.7 Typical Characteristics: $V_S = \pm 5 V$ (continued)





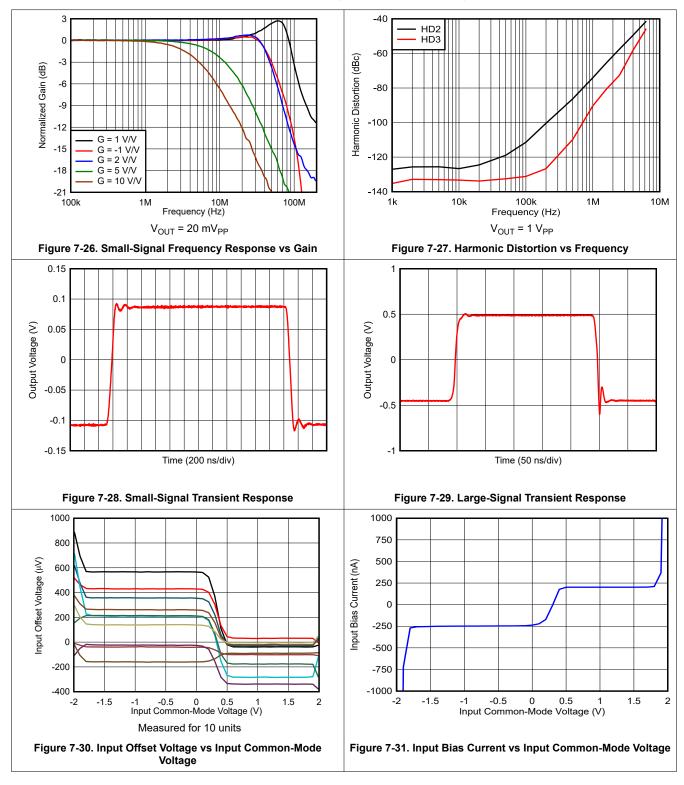
7.7 Typical Characteristics: $V_S = \pm 5 V$ (continued)





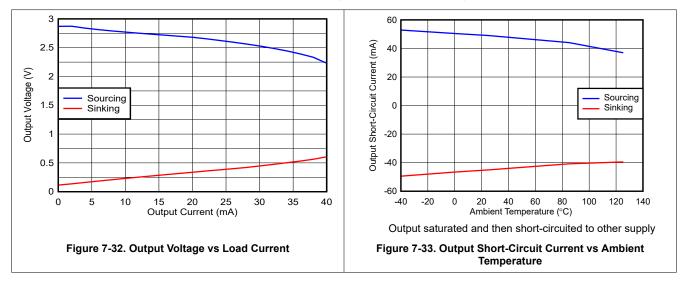
7.8 Typical Characteristics: V_S = 3 V

at V_{S+} = 3 V, V_{S-} = 0 V, G = 1 V/V, R_F = 0 Ω for G = 1 V/V, otherwise R_F = 1 k Ω for other gains, C_L = 1 pF, R_L = 2 k Ω connected to 1 V, input and output V_{CM} = 1 V, and $T_A \cong 25^{\circ}C$ (unless otherwise noted)



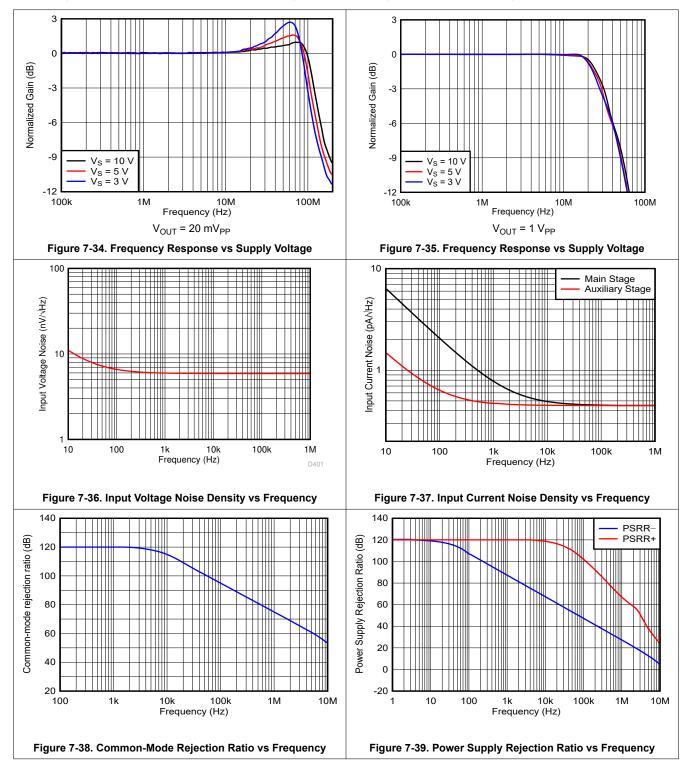
7.8 Typical Characteristics: V_S = 3 V (continued)

at V_{S^+} = 3 V, V_{S^-} = 0 V, G = 1 V/V, R_F = 0 Ω for G = 1 V/V, otherwise R_F = 1 k Ω for other gains, C_L = 1 pF, R_L = 2 k Ω connected to 1 V, input and output V_{CM} = 1 V, and $T_A \cong 25^{\circ}$ C (unless otherwise noted)



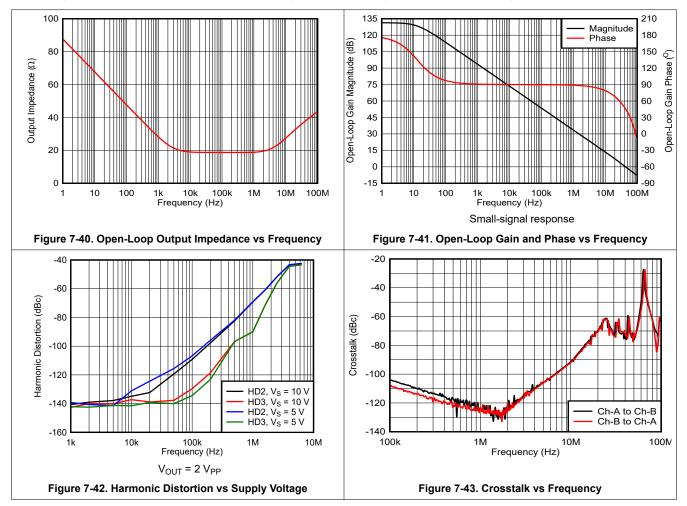


7.9 Typical Characteristics: $V_S = 3 V$ to 10 V





7.9 Typical Characteristics: $V_S = 3 V$ to 10 V (continued)





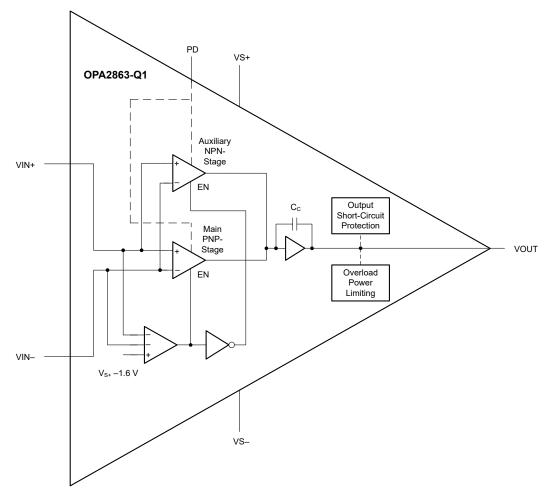
8 Detailed Description

8.1 Overview

The OPA2863-Q1 is a low-power, 50-MHz, rail-to-rail input and output (RRIO), bipolar, voltage-feedback operational amplifier with a voltage noise density of 5.9 nV/ \sqrt{Hz} and 1/f noise corner at 25 Hz. The OPA2863-Q1 works with a wide-supply voltage range of 2.7 V to 12.6 V, and consume only 700 µA quiescent current. The OPA2863-Q1 operates with a 2.7 V supply, is RRIO capable, consumes low-power, which makes this a great amplifier for 3.3-V or lower-voltage applications that require excellent ac performance. The main and auxiliary input stages of the amplifier are matched for gain bandwidth product (GBW), noise, and offset voltage and designed for applications that require wide dynamic input range and good SNR.

The device includes an overload power limit feature which limits the increase in quiescent current with overdriven and saturated outputs to either of the supply rails. For more details of this overload power limit feature, see Section 8.3.2.1. The output of the amplifier is protected against short-circuit fault conditions.

8.2 Functional Block Diagram





8.3 Feature Description

8.3.1 Input Stage

The OPA2863-Q1 includes a rail-to-rail input stage. The main stage differential pair using PNP bipolar transistors operates for common-mode input voltages from $V_{S-} - 0.2$ V to $V_{S+} - 1.6$ V. The amplifier inputs transition into the auxiliary stage using NPN transistors for common-mode input voltages from $V_{S+} - 1.6$ V till $V_{S+} + 0.2$ V. The PNP and NPN input stages offer a gain-bandwidth product of 50 MHz and a voltage noise density of 5.9 nV/ \sqrt{Hz} . The offset voltage for the two input stages is matched to lie within the device specifications. The auxiliary NPN input stage does not use the slew-boost circuit during large-signal transient response. The input bias current for the PNP and NPN input stages is opposite in polarity, which adds an additional offset based on the values of the gain-setting and feedback resistors. A common-mode input voltage transition between these input stages causes a crossover distortion that must be considered in high-frequency applications requiring excellent linearity. Limit the common-mode input voltage to $V_{S+} - 1.6$ V (maximum) for main-stage operation across process and ambient temperature.

The OPA2863-Q1 is a bipolar amplifier; therefore, the two inputs are protected with antiparallel back-to-back diodes between them, which limits the maximum input differential voltage to 1 V. The amplifier is slew limited, and the two inputs are pulled apart up to 1 V when the antiparallel diodes begin to conduct in very fast input or output transient conditions. Make sure to use gain-setting and feedback resistors large enough to limit the current through these diodes in such conditions.

8.3.2 Output Stage

The OPA2863-Q1 features a rail-to-rail output stage with possible signal swing from V_{S-} + 0.2 V to V_{S+} – 0.2 V. Violating the output headroom to either of the supplies causes output signal clipping and introduces distortion.

The OPA2863-Q1 integrates an output short-circuit protection circuit, which makes the device rugged for use in real-world applications.

8.3.2.1 Overload Power Limit

The OPA2863-Q1 includes overload power limiting that limits the increase in device quiescent current with output saturated to either of the supplies. Typically, when an amplifier output saturates, the two inputs are pulled apart, which can enable the slew-boost circuit. The input differential voltage is an error voltage in negative feedback that the amplifier core nullifies by engaging the slew-boost circuit and driving the output stage deeper into saturation. After the input to an amplifier attains a value large enough to saturate the output, any further increase in this input excitation results in a finite input differential voltage. As the output stage transistor is pushed deeper into saturation, the base-to-collector current gain (h_{FE}) drops with an increase in the base and collector current, and an increase in the device quiescent current. This increase in quiescent current can cause a catastrophic failure in multichannel, high-gain, high-density front-end designs, and reduce operating lifetime in portable, battery-powered systems.

The OPA2863-Q1 overload power limiting includes an intelligent output saturation-detection circuit that limits the device quiescent current to 2.2-mA per channel under dc overload conditions. This increase in quiescent current is smaller with ac input or output and output saturation duration for only a fraction of the overall signal time period. Table 8-1 compares the increase in quiescent current with 50-mV input overdrive for OPA2863-Q1 and other voltage-feedback amplifiers without overload power limit.

DEVICE	INPUT DIFFERENTIAL VOLTAGE	QUIESCENT CURRENT DURING OVERLOAD	INCREASE IN I _Q FROM STEADY- STATE CONDITION
OPA2863-Q1 with overload power limit	50 mV	1.1 mA	1.57 ×
Competitor amplifier without overload power limit	50 mV	1.96 mA	3.43 ×

Table 8-1. Quiescent Current with Saturated Outputs



8.3.3 ESD Protection

Figure 8-1 shows that all device pins are protected with internal ESD protection diodes to the power supplies. These diodes provide moderate protection to input overdrive voltages greater than the supplies. The protection diodes typically support 10-mA continuous input and output currents. Use series current limiting resistors if input voltages exceeding the supply voltages occur at the amplifier inputs, which makes sure that the current through the ESD diodes remains within the rated value. OPA2863-Q1 is a bipolar amplifier; therefore, the two inputs are protected with antiparallel, back-to-back diodes between the inputs that limits the maximum input differential voltage to approximately 1 V. Make sure to use gain-setting and feedback resistors large enough to limit the current through these diodes in fast slewing conditions.

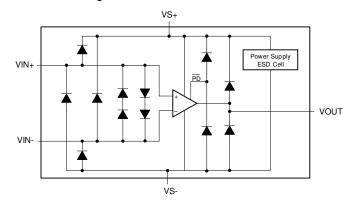


Figure 8-1. Internal ESD Protection

8.4 Device Functional Modes

The OPAx863-Q1 is operational with a supply voltage greater than 2.7 V (\pm 1.35 V). The maximum recommended supply voltage is 12.6 V (\pm 6.3 V). The OPAx863-Q1 can be used with unipolar, bipolar or asymmetric supplies.



9 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

9.1 Application Information

The OPA2863-Q1 is a classic voltage-feedback amplifier with two high-impedance inputs and a low-impedance output. This device has a GBW of 50 MHz, 5.9 nV/vHz of noise, RRIO capability, and precision performance, consuming only 700 µA quiescent current per channel. These features make the OPA2863-Q1 an excellent choice for use in low-side current sensing, ADC input driver, and reference buffering with fast settling, buffers, high gain and filter circuits. The overload power limit makes the OPA2863-Q1 truly low-power in high-gain, multichannel systems, limiting any increase in guiescent current during output overload conditions.

9.2 Typical Applications

9.2.1 Low-Side Current Sensing

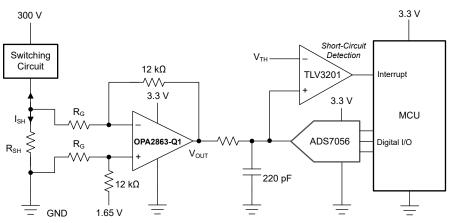


Figure 9-1. Low-Side Current Sensing in Power Converters

Power converters use current-mode feedback control for excellent transient response and multiphase load sharing. Inverter stages control the phase currents for torque control in motor drives. As a result of the simplicity and low-cost, many of these topologies use difference-amplifier-based, low-side current sensing. Figure 9-1 shows the use of the OPA2863-Q1 in a difference amplifier circuit for low-side current sensing.

9.2.1.1 Design Requirements

Table 9-1. Design Requirements							
PARAMETER	DESIGN REQUIREMENT						
Shunt resistor	10 mΩ						
Input current	15 A _{PP}						
Output voltage	3 V _{PP}						
Switching frequency	50 kHz						
Data acquisition	1 MSPS with 0.1% accuracy						
Input voltage due to ground bounce	10 Vpk						

Table 9-1	. Design	Requirements
-----------	----------	--------------



9.2.1.2 Detailed Design Procedure

In a difference amplifier circuit, the output voltage is given by:

$$V_0 = \frac{R_F}{R_G} I_{SH} R_{SH} + V_{REF}$$
(1)

For lowest system noise, small values of R_F and R_G are preferred. The smallest value of R_G is limited by the input transient voltage (10 V here) seen by the circuit, and is given by:

$$R_{G} = \frac{V_{IN}(max) - V_{D} - V_{S}}{I_{D}(max)}$$
(2)

where

- V_{IN(maximum)} is the maximum input transient voltage seen by the circuit
- V_D is the forward voltage drop of ESD diodes at the amplifier input
- I_{D(maximum)} is the maximum current rating of the ESD diodes at the amplifier input

For a difference amplifier gain of 20 V/V, an R_F of 12 k Ω and R_G of 600 Ω are used. With a clock frequency of 40 MHz and ADS7056 sampling at 1 MSPS, the available acquisition time for amplifier output settling is 550 ns. Table 9-1 shows the simulation results for the circuit in Figure 9-1. The worst-case peak-to-peak input transient condition is simulated. The output of the OPA2863-Q1 settles to within 0.1% accuracy within 543 ns. If using a slower clock frequency with the ADC is desired, then the acquisition time reduces with the same sampling rate, which degrades measurement accuracy. Alternatively, the sampling rate can be reduced to recover the required acquisition time and 0.1% accuracy.

9.2.1.3 Application Curve

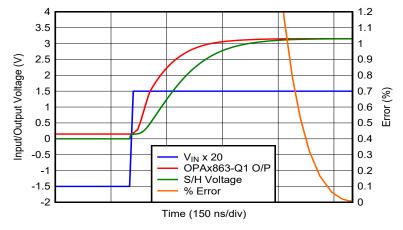


Figure 9-2. 0.1% Settling Performance



9.2.2 Front-End Gain and Filtering

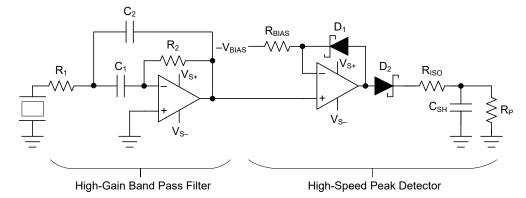


Figure 9-3. High-Gain Narrow Bandpass Filter and Peak Detector Circuit

Ultrasonic signaling is used for proximity and obstacle detection, level sensing, sonars, and so forth. Such signal chains detect the amplitude of received ultrasonic signal at a particular center frequency. Figure 9-3 shows a high-gain narrow bandpass filter and peak detector circuit using the OPA2863-Q1. The signal at the frequency of interest is filtered out, gained, and peak detected to report the amplitude at the output of this circuit. The phase information is lost in this circuit. The OPA2863-Q1 is used with the 50-MHz GBW to add a single-stage gain, and the peak detection capability is easily made with the RRIO capability of these amplifiers.

9.3 Power Supply Recommendations

The OPA2863-Q1 is intended to operate on supplies ranging from 2.7 V to 12.6 V. The OPA2863-Q1 operates on single-sided supplies, split and balanced bipolar supplies, or unbalanced bipolar supplies. Operating from a single supply has numerous advantages. The dc errors, due to the –PSRR term, can be minimized with the negative supply at ground. Typically, ac performance improves slightly at 10-V operation with minimal increase in supply current. Minimize the distance (< 0.1 in) from the power supply pins to high-frequency, 0.01-µF decoupling capacitors. A larger capacitor (2.2 µF typical) is used along with a high-frequency, 0.01-µF supply-decoupling capacitor at the device supply pins. Only the positive supply has these capacitors for single-supply operation. Use these capacitors from each supply to ground when a split-supply is used. If necessary, place the larger capacitors further from the device and share these capacitors among several devices in the same area of the printed circuit board (PCB). An optional supply decoupling capacitor across the two power supplies (for split-supply operation) reduces second harmonic distortion.



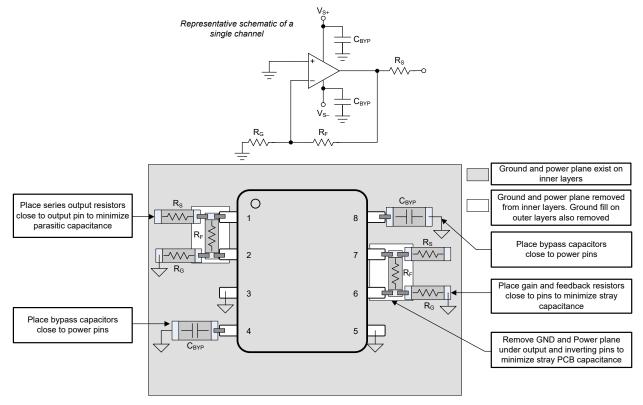
9.4 Layout

9.4.1 Layout Guidelines

Achieving optimum performance with a high-frequency amplifier (like the OPA2863-Q1) requires careful attention to board layout parasitics and external component types. The *DEM-OPA-SO-2A Demonstration Fixture* user's guide can be used as a reference when designing the circuit board. Recommendations that optimize performance include the following:

- 1. **Minimize parasitic capacitance** to any AC ground for all of the signal I/O pins. Parasitic capacitance on the output and inverting input pins can cause instability—on the noninverting input, parasitic capacitance can react with the source impedance to cause unintentional band-limiting. Open a window around the signal I/O pins in all of the ground and power planes around those pins to reduce unwanted capacitance. Otherwise, ground and power planes must be unbroken elsewhere on the board.
- 2. Minimize the distance (< 0.1 in) from the power-supply pins to high-frequency 0.01-μF decoupling capacitors. Avoid narrow power and ground traces to minimize inductance between the pins and the decoupling capacitors. The power-supply connections must always be decoupled with these capacitors. Larger (2.2-μF to 6.8-μF) decoupling capacitors, effective at lower frequency, must also be used on the supply pins. These capacitors can be placed somewhat farther from the device and shared among several devices in the same area of the PCB.</p>
- 3. Careful selection and placement of external components preserves the high-frequency performance of the OPA2863-Q1. Resistors must be a low reactance type. Surface-mount resistors work best and allow a tighter overall layout. Other network components, such as noninverting input termination resistors, must also be placed close to the package. Keep resistor values as low as possible and consistent with load-driving considerations. Lowering the resistor values keeps the resistor noise terms low and minimizes the effect of the parasitic capacitance. Lower resistor values, however, increase the dynamic power consumption because R_F and R_G become part of the amplifier output load network.

9.4.2 Layout Example







10 Device and Documentation Support

10.1 Documentation Support

10.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, DEM-OPA-SO-2A Demonstration Fixture user's guide
- Texas Instruments, Single-Supply Op Amp Design Techniques application report

10.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

10.3 Support Resources

TI E2E[™] support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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10.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.6 Glossary

TI Glossary This glossary lists and explains terms, acronyms, and definitions.

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.



PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
OPA2863QDRQ1	Active	Production	SOIC (D) 8	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	O2863Q
OPA2863QDRQ1.B	Active	Production	SOIC (D) 8	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	O2863Q

⁽¹⁾ **Status:** For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF OPA2863-Q1 :

Catalog : OPA2863



NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product



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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2863QDRQ1	SOIC	D	8	3000	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



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PACKAGE MATERIALS INFORMATION

24-Jul-2025



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2863QDRQ1	SOIC	D	8	3000	353.0	353.0	32.0

D0008A



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.

- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



D0008A

EXAMPLE BOARD LAYOUT

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



D0008A

EXAMPLE STENCIL DESIGN

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

9. Board assembly site may have different recommendations for stencil design.



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